

N-Channel NexFET™ Power MOSFET

FEATURES

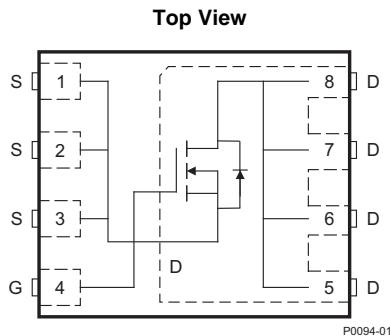
- Ultralow Q_g and Q_{gd}
- Low Thermal Resistance
- Avalanche Rated
- SON 5-mm × 6-mm Plastic Package

APPLICATIONS

- Point-of-Load Synchronous Buck in Networking, Telecom and Computing Systems
- Optimized for Control FET Applications

DESCRIPTION

The NexFET™ power MOSFET has been designed to minimize losses in power conversion applications.



PRODUCT SUMMARY

V_{DS}	Drain-to-source voltage	25	V
Q_g	Gate charge, total (4.5 V)	6.7	nC
Q_{gd}	Gate charge, gate-to-drain	1.9	nC
$r_{DS(on)}$	Drain-to-source on-resistance	$V_{GS} = 4.5$ V	5.4
		$V_{GS} = 10$ V	3.6
$V_{GS(th)}$	Threshold voltage	1.8	V

ORDERING INFORMATION

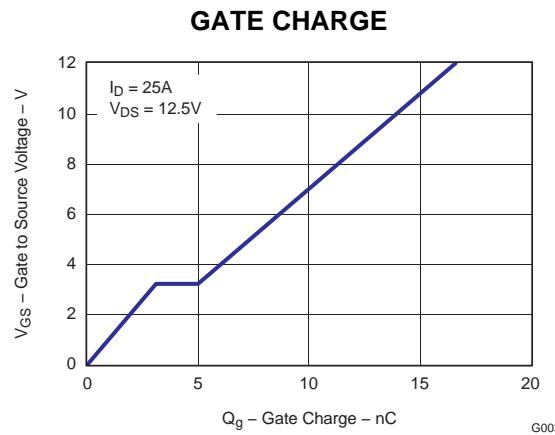
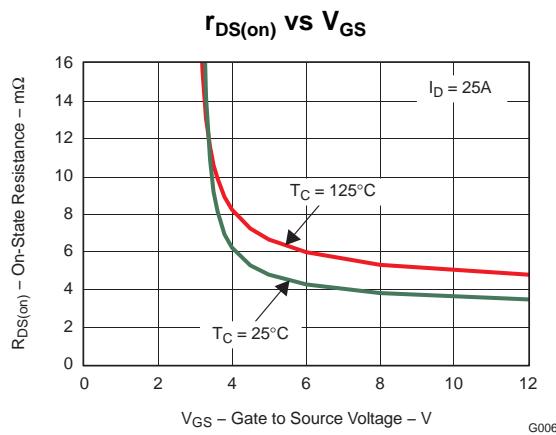
Device	Package	Media	Qty	Ship
CSD16408Q5	SON 5-mm × 6-mm plastic package	13-inch (33-cm) reel	2500	Tape and reel

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$ unless otherwise stated		VALUE	UNIT
V_{DS}	Drain-to-source voltage	25	V
V_{GS}	Gate-to-source voltage	-12 to 16	V
I_D	Continuous drain current, $T_C = 25^\circ\text{C}$	113	A
	Continuous drain current ⁽¹⁾	22	A
I_{DM}	Pulsed drain current, $T_A = 25^\circ\text{C}$ ⁽²⁾	141	A
P_D	Power dissipation ⁽¹⁾	3.1	W
T_J , T_{STG}	Operating junction and storage temperature range	-55 to 150	°C
E_{AS}	Avalanche energy, single-pulse $I_D = 23$ A, $L = 0.1$ mH, $R_G = 25$ Ω	126	mJ

(1) Typical $R_{DS(on)} = 41^\circ\text{C}/\text{W}$ on 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu pad on a 0.06-inch (1.52-mm) thick FR4 PCB.

(2) Pulse duration ≤ 300 μs, duty cycle $\leq 2\%$



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ELECTRICAL CHARACTERISTICS

$T_A = 25^\circ\text{C}$ unless otherwise stated

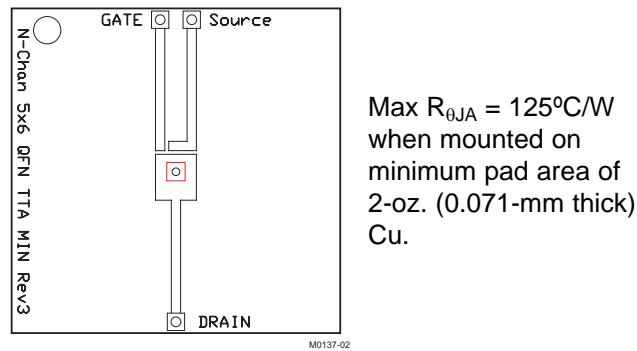
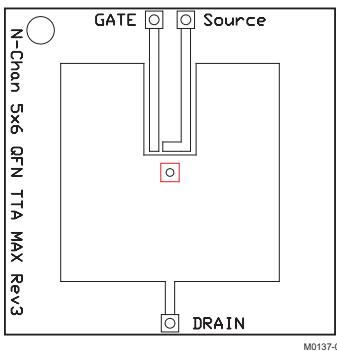
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Static Characteristics						
BV_{DSS}	Drain-to-source voltage	$V_{\text{GS}} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	25			V
I_{DSS}	Drain-to-source leakage	$V_{\text{GS}} = 0 \text{ V}$, $V_{\text{DS}} = 20 \text{ V}$		1		μA
I_{GSS}	Gate-to-source leakage	$V_{\text{DS}} = 0 \text{ V}$, $V_{\text{GS}} = -12 \text{ V}$ to 16 V		100		nA
$V_{\text{GS}(\text{th})}$	Gate-to-source threshold voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250 \mu\text{A}$	1.4	1.8	2.1	V
$r_{\text{DS}(\text{on})}$	Drain-to-source on-resistance	$V_{\text{GS}} = 4.5 \text{ V}$, $I_D = 25 \text{ A}$		5.4	6.8	$\text{m}\Omega$
		$V_{\text{GS}} = 10 \text{ V}$, $I_D = 25 \text{ A}$		3.6	4.5	$\text{m}\Omega$
g_{fs}	Transconductance	$V_{\text{DS}} = 15 \text{ V}$, $I_D = 25 \text{ A}$		60		S
Dynamic Characteristics						
C_{iss}	Input capacitance	$V_{\text{GS}} = 0 \text{ V}$, $V_{\text{DS}} = 12.5 \text{ V}$, $f = 1 \text{ MHz}$	990	1300		pF
C_{oss}	Output capacitance		760	1000		pF
C_{rss}	Reverse transfer capacitance		75	100		pF
R_g	Series gate resistance		0.8	1.6		Ω
Q_g	Gate charge total (4.5 V)		6.7	8.9		nC
Q_{gd}	Gate charge, gate-to-drain		1.9			nC
Q_{gs}	Gate charge, gate-to-source	$V_{\text{DS}} = 12.5 \text{ V}$, $I_D = 25 \text{ A}$	3.1			nC
$Q_{\text{g}(\text{th})}$	Gate charge at V_{th}		1.8			nC
Q_{oss}	Output charge		15.7			nC
$t_{\text{d}(\text{on})}$	Turnon delay time		11.3			ns
t_r	Rise time	$V_{\text{DS}} = 12.5 \text{ V}$, $V_{\text{GS}} = 4.5 \text{ V}$, $I_D = 20 \text{ A}$, $R_G = 2 \Omega$	25			ns
$t_{\text{d}(\text{off})}$	Turnoff delay time		11			ns
t_f	Fall time		10.8			ns
Diode Characteristics						
V_{SD}	Diode forward voltage	$I_S = 25 \text{ A}$, $V_{\text{GS}} = 0 \text{ V}$	0.8	1		V
Q_{rr}	Reverse recovery charge	$V_{\text{DD}} = 13 \text{ V}$, $I_F = 25 \text{ A}$, $\text{di/dt} = 300 \text{ A}/\mu\text{s}$	17			nC
t_{rr}	Reverse recovery time	$V_{\text{DD}} = 13 \text{ V}$, $I_F = 25 \text{ A}$, $\text{di/dt} = 300 \text{ A}/\mu\text{s}$	21			ns

THERMAL CHARACTERISTICS

$T_A = 25^\circ\text{C}$ unless otherwise stated

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta\text{JC}}$	Thermal Resistance Junction to Case ⁽¹⁾		1.9		$^\circ\text{C}/\text{W}$
$R_{\theta\text{JA}}$	Thermal Resistance Junction to Ambient ⁽¹⁾ (2)		51		$^\circ\text{C}/\text{W}$

(1) $R_{\theta\text{JC}}$ is determined with the device mounted on a 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu pad on a 1.5-inch \times 1.5-inch (3.81-cm \times 3.81-cm), 0.06-inch (1.52-mm) thick FR4 PCB. $R_{\theta\text{JC}}$ is specified by design, whereas $R_{\theta\text{JA}}$ is determined by the user's board design.
 (2) Device mounted on FR4 material with 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu.



TYPICAL MOSFET CHARACTERISTICS

$T_A = 25^\circ\text{C}$ unless otherwise stated

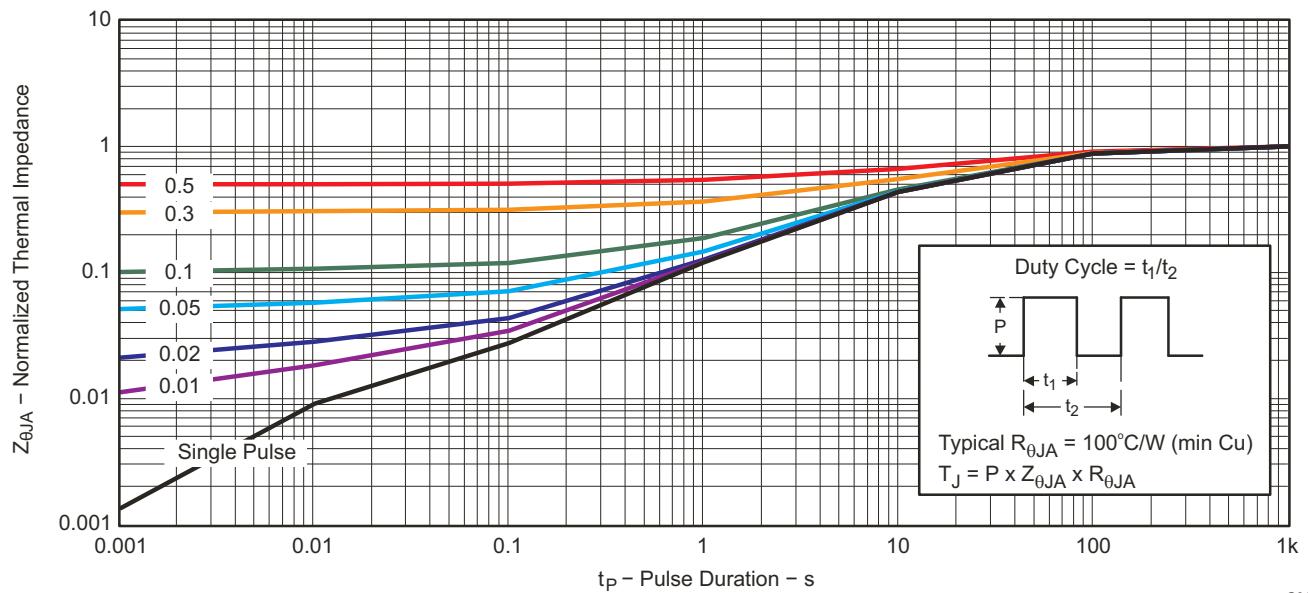


Figure 1. Transient Thermal Impedance

TYPICAL MOSFET CHARACTERISTICS (continued)

$T_A = 25^\circ\text{C}$ unless otherwise stated

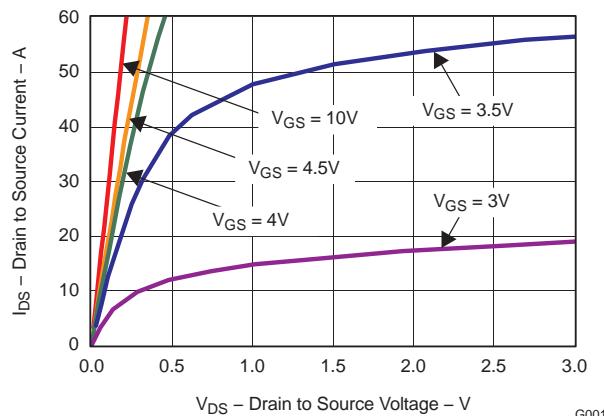


Figure 2. Saturation Characteristics

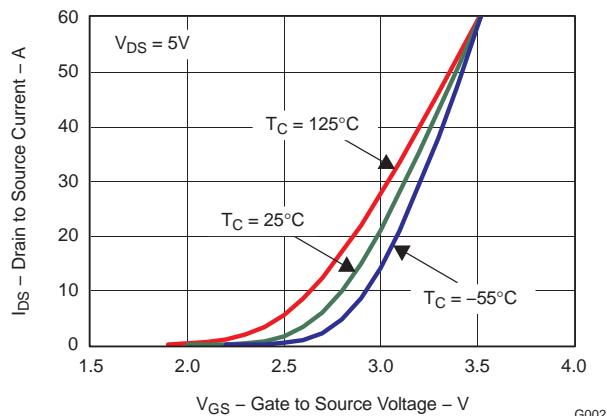


Figure 3. Transfer Characteristics

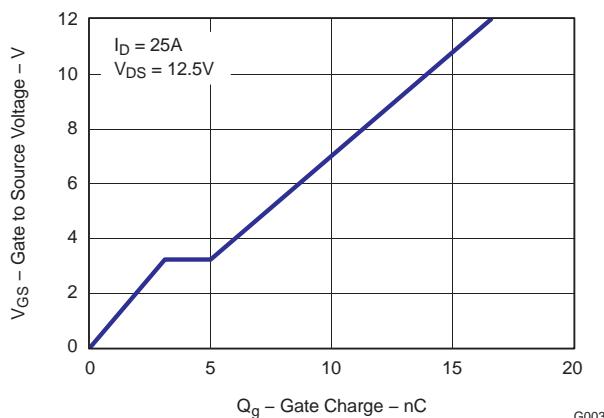


Figure 4. Gate Charge

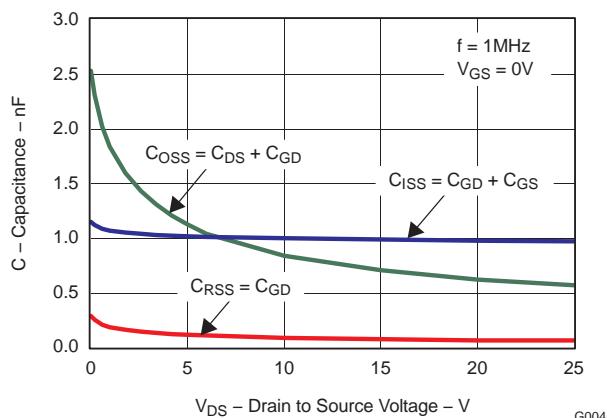


Figure 5. Capacitance

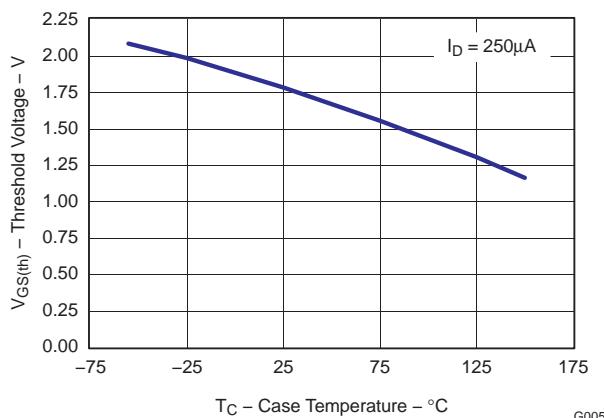


Figure 6. Threshold Voltage vs. Temperature

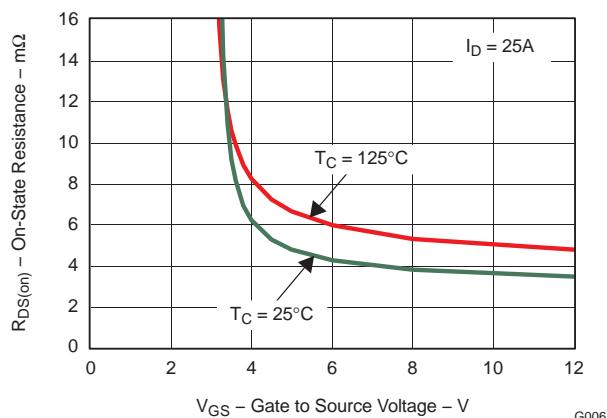


Figure 7. On-State Resistance vs. Gate-to-Source Voltage

TYPICAL MOSFET CHARACTERISTICS (continued)

$T_A = 25^\circ\text{C}$ unless otherwise stated

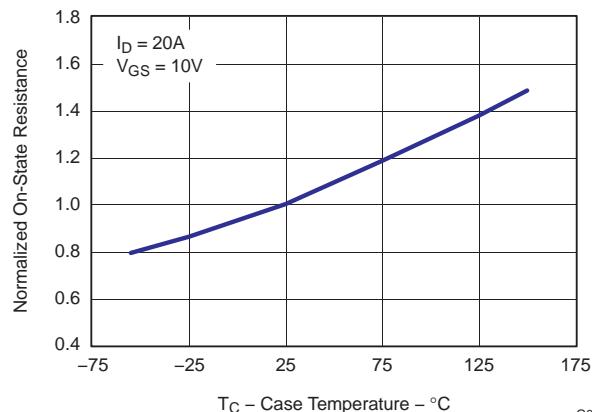


Figure 8. Normalized On-State Resistance vs. Temperature

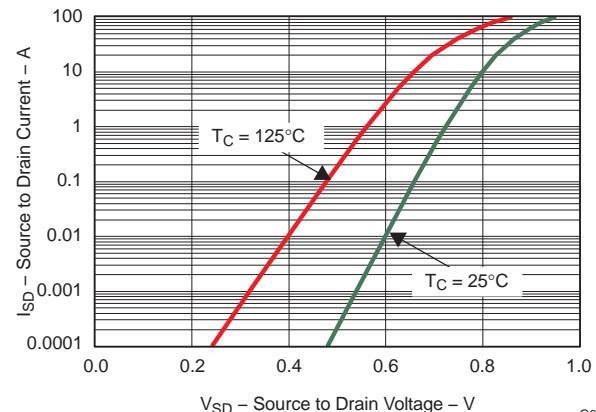


Figure 9. Typical Diode Forward Voltage

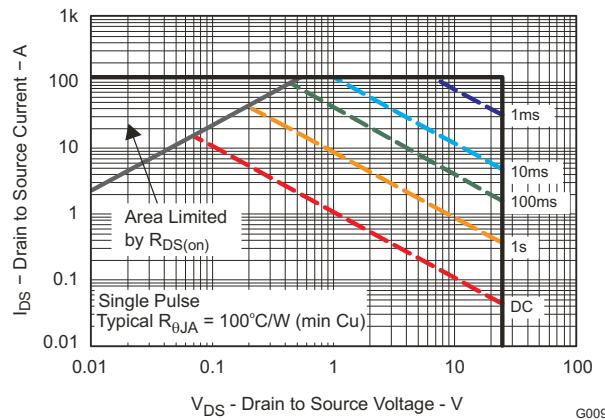


Figure 10. Maximum Safe Operating Area

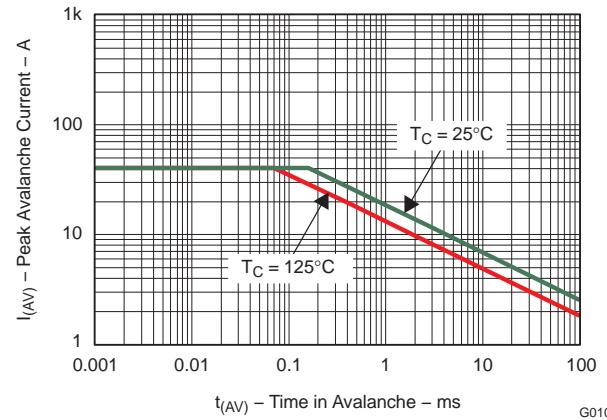


Figure 11. Single-Pulse Unclamped Inductive Switching

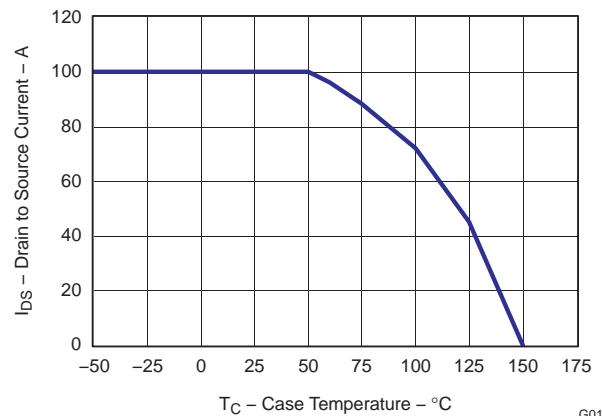
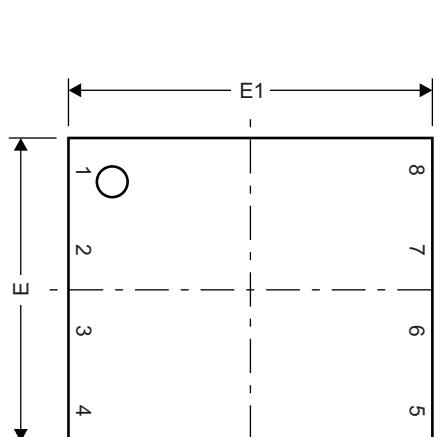


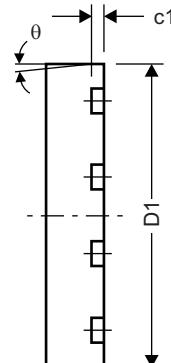
Figure 12. Maximum Drain Current vs. Temperature

MECHANICAL DATA

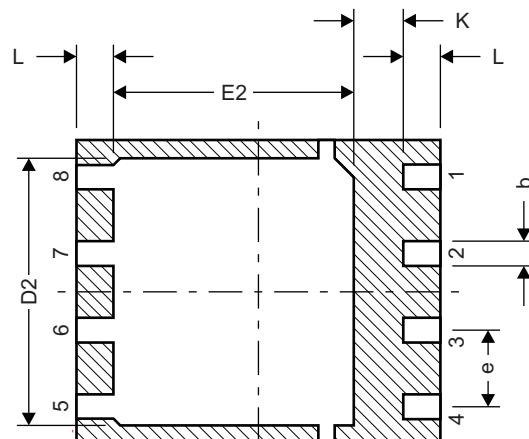
Q5 Package Dimensions



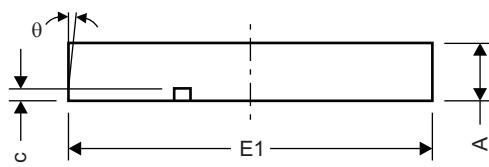
Top View



Side View



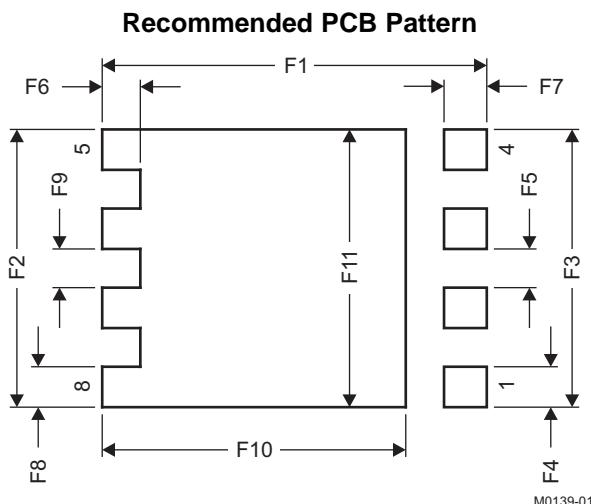
Bottom View



Front View

M0140-01

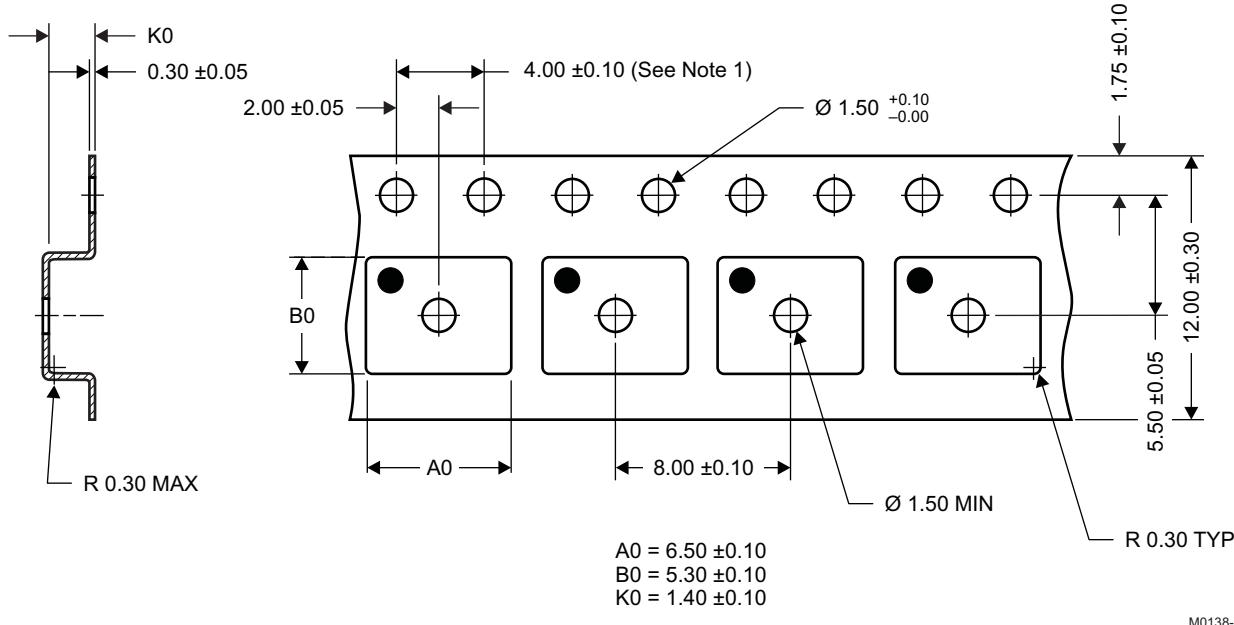
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.950	1.050	0.037	0.039
b	0.360	0.460	0.014	0.018
c	0.150	0.250	0.006	0.010
c1	0.150	0.250	0.006	0.010
D1	4.900	5.100	0.193	0.201
D2	4.320	4.520	0.170	0.178
E	4.900	5.100	0.193	0.201
E1	5.900	6.100	0.232	0.240
E2	3.920	4.12	0.154	0.162
e	1.27 typ		0.050	
L	0.510	0.710	0.020	0.028
theta	0.00	–	–	–



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
F1	6.205	6.305	0.244	0.248
F2	4.46	4.56	0.176	0.18
F3	4.46	4.56	0.176	0.18
F4	0.65	0.7	0.026	0.028
F5	0.62	0.67	0.024	0.026
F6	0.63	0.68	0.025	0.027
F7	0.7	0.8	0.028	0.031
F8	0.65	0.7	0.026	0.028
F9	0.62	0.67	0.024	0.026
F10	4.9	5	0.193	0.197
F11	4.46	4.56	0.176	0.18

For recommended circuit layout for PCB designs, see application note *Reducing Ringing Through PCB Layout Techniques* (SLPA005).

Q5 Tape and Reel Information



Notes:

1. 10-sprocket hole-pitch cumulative tolerance ± 0.2
2. Camber not to exceed 1 mm in 100 mm, noncumulative over 250 mm
3. Material: black static-dissipative polystyrene
4. All dimensions are in mm, unless otherwise specified.
5. A0 and B0 measured on a plane 0.3 mm above the bottom of the pocket
6. MSL1 260°C (IR and convection) PbF reflow compatible

REVISION HISTORY

Changes from Revision Original (October 2009) to Revision A	Page
• Deleted environmental bullets from features list	1
• Deleted package marking section from end of data sheet	7

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD16408Q5	ACTIVE	VSON-CLIP	DQH	8	2500	Pb-Free (RoHS Exempt)	SN	Level-1-260C-UNLIM	-55 to 150	CSD16408	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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